

ABSTRACT OF THE DISCLOSURE

Disclosed is a conductive composition used for a conductor of an electronic component, comprising a metal particle and a metal oxide particle which has an average particle size of 5 to 60 nm, a melting point of 1500°C or higher, and a content of 0.1 to 10.0 wt% based on the amount of the metal particle. According to the conductive composition, even when the metal particle is made fine, a sintering initiation temperature can be adequately increased, thus a generation of a crack and a de-lamination can be prevented easily and firmly.